

IN THE SPECIFICATION:

Kindly amend paragraph 17, as follows:

[0017] In the preferred embodiment of the invention, the solder bonded sputter target/backing plate assembly would be disc-shaped and have a plurality of segmented arcuate-shaped ridges spaced apart on different radii of the bonded surface of the disc-shaped backing plate. An alternate embodiment of the invention is to apply a plurality of segmented arcuate-shaped ridges spaced apart on different radii of the bonded surface of the disc-shaped sputter target-backing plate blank. Preferably, the backing plate and ridges are made of the same material and the height of the ridges will be constant so that a uniform thickness solder bonded interface spacing can be achieved. For most applications, the height of the ridges could vary between about 0.005 inch and about 0.050 inch, preferably between about 0.010 inch and about 0.030 inch and most preferably about 0.020 inch. The spacing of the ridges has to be sufficient to prevent bowing of the sputter target at the center, especially for thinner and large diameter sputter targets. The width of the ridges cannot be too wide since the bonding interface would be compromised or reduced by the surface area of the ridges. Thus the thickness of the width of the ridges could vary, depending on the application, between about 0.005 inch and about 0.050 inch, preferably between about 0.010 inch and about 0.030 inch and most preferably about 0.020 inch. The radial distance between adjacent arcuate shaped ridges can be between about 0.2 inch and about 2.0 inch, preferable about 1.0 inch. Preferably, the ratio of the area of

the top surface of the ridges to the area of the bonded surface of the target should be no more than 10 percent, preferably not more than 4 percent.